Claim 3 (twice amended), line 7, replace "Kevlar TM" with --Kevlar™--.

Claim 6 (Twice amended), line 2, after "μm" insert --across its surface diameter--.

Claim 7 (Twice amended), line 4, after "μm" insert --in diameter--.

20-22. (Amended) The method of claim 1 in which [each] a single pulse cleanly removes material from at least two layers within the spatial spot size.

Claim 26 (Amended), line 10, replace "Kevlar TM" with --Kevlar™--.

Claim 27 (Amended), line 2, delete "," and insert --in diameter and--.

Add the following claims.

24 --28. The method of claim 1 in which the target comprises a circuit board.--

4-4-29. The method of claim 3 in which the two layers comprise an organic dielectric material layer and a metal layer.--

17-30. The method of claim 26 in which the target comprises a circuit board.--

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REMARKS

Claims 1-13, 15-17, and 22-30 are in the application, of which only claim 1 is in independent form. Claims 1, 3, 6, 7, 22, 26, and 27 are amended. Claims 28-30 are added.

Claims 6, 7, and 27 stand rejected under 35 USC § 112, second paragraph, for being indefinite for failing to particularly point and distinctly claim the subject matter which the applicant regards as the invention. The Examiner states that "spot size" and "spatial region" denote two-dimensional areas, whereas "μm" is a measure of one-dimensional length. Applicant responds to this rejection as follows.

Claims 6, 7, and 27 have been amended to recite "diameter" in association with the one-dimensional lengths to clarify their relationship to